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**L'ETUDE ET L'EXPLOITATION DES PROCEDES
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(54) **Deposition of gallium containing thin films using new gallium precursors.**

(57) Compounds of formula (I): $[(R_a)(R_b)Ga(OR_c)]_x$,
wherein:

- R_a and R_b are independently selected in the group consisting of H, C1-C6 linear or branched alkyl, aryl or alkylsilyl;

- R_c is selected in the group consisting of C1-C4 linear or branched alkyl, aryl or alkylsilyl;

- x is an integer equal to 1 or 2.

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Description

[0001] This invention discloses new molecules containing gallium and deposition of gallium containing thin films by vapor phase deposition methods from the new molecules.

[0002] Gallium is a rare metal which is most commonly recovered from the zinc-sulfide mineral sphalerite. Despite its rarity, gallium is used in multitude of technical applications from electronic to photovoltaic and optical devices. Gallium is dominantly used in gallium tin oxide layers (GaTO) for flat panel displays, copper-gallium-selenide (CGaS) type of solar cells, indium-gallium-nitride (InGaN) as used for LEDs; blue-ray lasers and InGaP for optoelectronic devices. In contrast to GaTO and CGaS that are mainly deposited by PVD, InGaN is mainly deposited by metal-organic chemical vapor deposition (MOCVD).

[0003] In addition to above utilizations, gallium can also be used for other applications. The usage of Ga_2S_3 to replace CdS in a photovoltaic CGaS based stack: CGaS/CdS/ZnO/ZnO:Al to obtain a better cell efficiency is already known. Gallium is also reported to be used in phase-change materials (PCM) such as $Ge_2Sb_2Te_5$ (GST), to form gallium containing GST alloys to improve PCM characteristics such as data retention. Gallium can also be used in other PCM as Ga-Ge-Te (GaGT), Ga-Sb-Te (GaST), or AgGaSbTe. Alternatively, Ga_2Se_3 might be used for PCM fabrication. It is known that Ga_2Se_3 has a wider variation in electrical resistivity in comparison with the previous $Ge_2Sb_2Te_5$ and therefore could be an alternative to GST.

[0004] MOCVD and ALD are common techniques to deposit thin films that can also be used for GST depositions. These techniques require ideally stable and volatile precursors. Concerning metal precursors several sources of metal are described in literature:

- The deposition of InGaN by MOCVD from trimethyl-indium (TMI) is disclosed. Deposition from TMI of GaInP is already known. TMI is very volatile and reactive but is a pyrophoric compound. This last characteristic complicates its handling which requires special safety procedures.
- $InCl_3$ and InCl are probably the most simple indium precursors but their lack of volatility (sublimation of $InCl_3$: 133 Pa at 356°C) is a significant disadvantage. Another drawback is the generation of chlorine during deposition. Cl_2 will damage the deposited layer.
- InCp is another commercial indium source. This molecule is volatile but its main disadvantage is its heat sensitivity. Heating is necessary for vaporizing the compound and therefore decomposition will occur and a clogging of the distribution line is expected.
- $In(N_3)_3Py_3$ was characterized by TGA in the literature, to check the feasibility of using for InN deposition by MOCVD. It appears that the precursor decomposes firstly at 120°C and detonates at 300°C.

In a safety point of view, this behavior is not acceptable for an industrial usage.

- For InS deposition, the use of Indium acetylacetonate is known, but thermal analysis of this precursor shows a high level of residues after complete vaporization. This phenomenon will generate particles and clogging in the distribution lines.

[0005] In conclusion, there are no suitable non-pyrophoric gallium metal-organic compounds with the desired thermal behaviour to enable the vapor phase deposition of gallium containing thin films.

[0006] According to a first embodiment, the invention relates to compounds of formula (I): $[(R_a)(R_b)Ga(OR_c)]_x$, wherein:

- R_a and R_b are independently selected in the group consisting of H, C1-C6 linear or branched alkyl, aryl or alkylsilyl;
- R_c is selected in the group consisting of C1-C4 linear or branched alkyl, aryl or alkylsilyl;
- x is an integer equal to 1 or 2, preferably, $x = 2$.

[0007] According to another embodiment, the invention concerns compounds as defined above wherein R_a and R_b are a methyl or an ethyl group.

[0008] According to another embodiment, the invention concerns compounds as defined above wherein R_c is chosen between methyl, ethyl, iso-propyl and tert-butyl.

[0009] According to another embodiment, the invention concerns the compounds: $Me_2Ga(OMe)_2$, $[Me_2Ga(OtBu)]_2$, $[Me_2Ga(OEt)]_2$, $[Me_2Ga(OiPr)]_2$, $[Et_2Ga(OtBu)]_2$. According to another embodiment, the invention concerns a method for forming a gallium containing thin film on a substrate comprising at least the steps of:

- a) providing a vapor comprising at least one precursor compound of the formula (I) as defined above;
- b) reacting the vapor comprising the at least one compound of formula (I) with the substrate, according to an atomic layer deposition process, to form a layer of a gallium-containing complex on at least one surface of said substrate.

[0010] According to another embodiment, the invention concerns a method as defined above further comprising the step:

- c) reaction of the complex formed obtained in step b) with a reagent selected from another metal source, reducing reactants and/or nitriding reactants and/or oxidizing reactants.

[0011] According to another embodiment, the invention concerns a method of manufacturing a semiconductor structure, comprising the steps of the method defined above, wherein the substrate is a semiconductor sub-

strate.

[0012] According to another embodiment, the invention concerns a method of manufacturing a photovoltaic structure, comprising the steps of the method defined above, wherein the substrate is a photovoltaic substrate.

[0013] According to another embodiment, the invention concerns the use of at least one compound as defined above for the manufacturing of phase change materials (PCM).

[0014] The new gallium metal-organic compounds present at least the following features:

- 1) controlling the steric bulk of Rc will enable to form monomeric compounds;
- 2) being liquid or being easily sublimized or having a melting point below 180°C;
- 3) being thermally stable (see figure 1);
- 4) having sufficient volatility for vapor phase distribution (see figure 2);
- 5) enabling the deposition by ALD of gallium containing thin films such as Ga-doped GST, Ga₂Se₃, InGaN,...;
- 6) avoiding the pyrophoricity.

[0015] The present invention introduces the using of a low melting point, volatile and thermally stable gallium compounds to deposit gallium containing thin films by either ALD process.

[0016] According to another embodiment of the invention, the family of gallium precursor of the present invention can be used for the deposition of gallium containing thin films by (MO)CVD (Metal-Organic Chemical Vapor Deposition) and derivatives.

[0017] Surprisingly, this novel family of metal-organic compounds presents particularly attractive thermal properties. As a matter of fact, the new precursors present the advantages of:

- 1) being liquid at room temperature or having a melting point lower than 180°C;
- 2) being thermally stable enough to enable proper distribution (gas phase or direct liquid injection) without particles generation;
- 3) being thermally stable enough to allow wide self-limited ALD window (see figure 1);
- 4) allowing to deposit a variety of gallium containing thin films, including binary, ternary or quaternary materials. Gallium can also be used as dopant. To obtain a thin film with the expected composition and physical properties, the precursor can be used in combination with a co-reactant or combination of co-reactants. The co-reactants are selected without limitation among the group consisting of O₂, Plasma O₂, H₂O, O₃, N₂, NH₃, hydrazine and alkyl derivatives, N-containing radicals (for instance N., NH., NH₂.), NO, N₂O, NO₂, amines, GeCl₂, SbCl₃, TeCl₄, TDMAGe, TDMASb, DIPT...;
- 5) having sufficient volatility for vapor phase distribution

(see figure 2);

6) enabling the deposition by ALD of gallium containing thin films such as Ga-doped GST, Ga₂Se₃, InGaN,...

[0018] Those skilled in the art will recognize that the novel metal-organic compounds could be used in various applications fields such as electronic, photovoltaic, optoelectronic devices.

Method of depositing gallium containing thin films:

[0019] The deposition of a gallium containing film is performed in several steps:

a. Vaporizing a gallium source to form a gas-phase gallium source.

b. Introducing several precursors in vapor phase in a deposition device, wherein said precursors comprise said vaporized gallium source, and may comprise another metal source, an oxygen source, a nitrogen source, a germanium source, an antimony source, a tellurium source or a selenium source to form an gallium containing film.

1. In one embodiment of the invention, the precursor is stored in a heated canister. The vaporization of the precursor can be realized by introducing a gas in the said canister. The canister is preferably heated at a temperature which allows liquefying or subliming the said precursor with a sufficient vapor pressure. The carrier gas can be selected, from Ar, He, H₂, N₂ or mixtures of them. The carrier gas flow is in the range of 1 mL/min to 1 L/min. The canister can for instance be heated at temperatures in the range of 20°C to 180°C. The temperature can be adjusted to control the amount of precursor in the gas phase.

2. In one embodiment of the invention, the precursor is stored in a heated canister. The vaporization of the precursor can be realized by drawing the vapour to the reactor chamber without using a carrier gas flow.

3. In another embodiment of the invention, the said precursor source is fed in the liquid state to a vaporizer where it is vaporized.

4. In another embodiment, the said precursor can be mixed with a stabilizer.

5. The said precursor source can be mixed to a solvent or a mixture of solvent. The said solvent can be selected from the group consisting of octane, hexane, pentane, tetramethylsilane, mes-

ithylene, and other aromatic solvents. This mixture is contained in a canister which can be heated at a temperature in the range of 20°C to 180°C.

6. In another embodiment of the invention, the said precursor source can be mixed to a solvent or a mixture of solvents and one or more other metal source. The said solvent can be selected from the group consisting of octane, hexane, pentane, tetramethylsilane, mesithylene and other aromatic solvents. This mixture is contained in a canister which can be heated at a temperature in the range of 20°C to 180°C.

7. In another embodiment of the invention, the said mixtures are fed in the liquid state to a vaporizer where they are vaporized.

8. In another embodiment of the invention, the said mixtures can be mixed with a stabilizer.

9. In one embodiment of the invention, the pressure in the said canister is in the range from 0.1 Pa to 101300 Pa (related to 1 to 4).

10. In one embodiment of the invention, the pressure in the said canister is in the range from 100000 Pa to 400000 Pa (related to 5 to 7).

11. The said vaporized metal source is introduced into a reaction chamber where it is contacted to a substrate. The substrate can be selected from the group consisting of Si, SiO₂, SiN, SiON, and other metal containing films. The substrate can be heated to sufficient temperature to obtain the desired film at sufficient growth rate and with desired physical state and composition. Typical temperature range from 50°C to 600°C. Preferably the temperature is lower or equal to 450°C. The pressure in the reaction chamber is controlled to obtain the desired metal containing film at sufficient growth rate. Typical pressure range from 0.1 Pa to 13300 Pa or higher. The metal source gas flow is in the range of 1 mL/min to 1 L/min.

12. In one embodiment of the invention, the said new precursor source or the mixture described in 4, 5, 6, and 8 is mixed to one or more reactant species prior to the reaction chamber.

13. In one embodiment of the invention, the said new precursor source or the mixture described in 4, 5, 6, and 8 is mixed to one or more reactant species in the reaction chamber.

14. In another embodiment of the invention, the

said new precursor and the reactant species can be introduced simultaneously (chemical vapor deposition), sequentially (atomic layer deposition) or different combinations. One example is to introduce metal source and the other metal source together in one pulse and co-reactant in a separate pulse (modified atomic layer deposition); another example is to introduce the reactant species (one example could be oxygen) continuously and to introduce metal source by pulse (pulsed-chemical vapor deposition). Typical temperature range from 50°C to 600°C. Preferably the temperature is lower or equal to 450°C. The pressure in the reaction chamber is controlled to obtain the desired metal containing film at sufficient growth rate. Typical pressure range from 10.1 Pa to 13300 Pa or higher. For each reactant, the gas flow is in the range of 1 mL/min to 1 L/min.

15. In one embodiment of the invention, the reactant species are passed through a plasma system localized remotely from the reaction chamber, and decomposed to radicals.

16. In one embodiment of the invention where the targeted metal based film contains oxygen, such as for example Ga₂O₃ the said reactant species include an oxygen source which is selected from, but not limited to, oxygen (O₂), oxygen radicals (for instance O. or OH.), for instance generated by a remote plasma, ozone (O₃), moisture (H₂O) and H₂O₂.

17. In one embodiment of the invention where the targeted metal based film contains nitrogen such as InGa₂N, one or more reactant species containing nitrogen can be used. The said reactant species are selected from, but not limited to, nitrogen (N₂), ammonia, hydrazine and alkyl derivatives, N-containing radicals (for instance N., NH., NH₂.), NO, N₂O, NO₂, amines.

18. In one embodiment of the invention, the said metal sources are simultaneously introduced and mixed into the reaction chamber.

19. In another embodiment of the invention, the said metal sources are simultaneously introduced and mixed to reactant species into the reaction chamber.

20. In one embodiment of the invention, the other metal sources are selected in the group of, but without limitation, GeCl₂, SbCl₃, TeCl₄, TD-MAGe, TDMASb, DIPT...

21. In one embodiment of the invention, the said

precursor is used for atomic layer deposition of gallium containing films. The said gallium source, the possible said metal source and the reactant species are introduced sequentially in the reaction chamber (atomic layer deposition). The reactor pressure is selected in the range from 0.1 Pa to 13300 Pa. Preferably, the reactor pressure is comprised between 133 Pa and 1330 Pa. A purge gas is introduced between the metal source pulse and the reactant species pulse. The purge gas can be selected without limitation from the group consisting of N₂, Ar, He. The purge gas flow is in the range 100mL/min to 10L/min. The metal source, purge gas and reactant species pulse duration is comprised between 0.1 and 100 s. Preferably, the pulse duration is comprised between 0.5 s and 10 s.

22. In another embodiment of the invention, the deposition of the gallium containing thin film is performed by a combination of the previous elements (points 1 to 21).

EXAMPLES

A. Synthesis of [Me₂GaOtBu]₂

[0020] All operations are carried in an inert gas filled glove box. 0.522g (7.04 mmol) of tBuOH are dissolved in 4 mL of Et₂O. 1.48g (7.04 mmol) of Me₂GaC₅H₅ are dissolved in approximately 10 mL of Et₂O. The solution of tBuOH/Et₂O is added to Me₂GaC₅H₅. The mixture is stirred for 1h at room temperature before the volatile materials are removed by distillation under vacuum. A sublimation at 35°C leads to 1.51 g of Me₂Ga(OtBu) as a colorless waxy solid.

B. Deposition of a gallium-oxide layer by ALD

[0021] The indium oxide is deposited at 180°C on a sapphire substrate using [Me₂Ga(OtBu)]₂ and ozone as reactive gas. The precursor is stored into canisters and sublimed at 50°C. N₂ is used as carrier gas. The precursor and reactive gas are sequentially introduced into the reactor. A film of indium oxide is obtained.

D. Thermal characterization of [Me₂GaOtBu]₂

[0022] Figure 1 shows that the precursor is thermally stable at least until 200°C; and Figure 2 shows that it presents sufficient volatility for vapour phase distribution 1100 Pa (8 Torr) at 100°C.

[0023] Consequently, [Me₂GaOtBu]₂ is thermally stable and has a good volatility at the same time in addition of the fact that it is not a pyrophoric compound.

E. Pyrophoricity test of [Me₂GaOtBu]₂

[0024] A sampling is performed in a glovebox under argon with a controlled level of oxygen and moisture (below 5 ppm). 250mg of powder are placed in a small glass crystallizer. The crystallizer is then placed in a leak proof screw cap jar during the transfer from the glovebox to a fume hood. The screw cap jar is opened under the fume hood and the crystallizer with the powder is placed directly in contact with air. No fumes are seen but there are some odours of amine (HNMe₂). After 1 min, some drops of water are deposited directly on the product. Some bubbles are seen on the powder but without violent reaction.

[0025] We conclude that the product is not pyrophoric.

Claims

1. Compounds of formula (I): [(R_a)(R_b)Ga(OR_c)]_x, wherein:

- R_a and R_b are independently selected in the group consisting of H, C1-C6 linear or branched alkyl, aryl or alkylsilyl;
- R_c is selected in the group consisting of C1-C4 linear or branched alkyl, aryl or alkylsilyl;
- x is an integer equal to 1 or 2.

2. Compounds according to Claim 1, wherein x = 2.

3. Compounds according to Claim 1 or 2, wherein R_a and R_b are a methyl or an ethyl group.

4. Compounds according to one of Claims 1 to 3, wherein R_c is chosen between methyl, ethyl, isopropyl and tert-butyl.

5. The following compounds: Me₂Ga(OMe)]₂, [Me₂Ga(OtBu)]₂, [Me₂Ga((OEt)]₂, [Me₂Ga(OiPr)]₂, [Et₂Ga(OtBu)]₂.

6. Method for forming a gallium containing thin film on a substrate comprising at least the steps of:

- a) providing a vapor comprising at least one precursor compound of the formula (I) as defined in one of claims 1 to 5;
- b) reacting the vapor comprising the at least one compound of formula (I) with the substrate, according to an atomic layer deposition process, to form a layer of a gallium-containing complex on at least one surface of said substrate.

7. Method according to Claim 6 further comprising the step:

- c) reaction of the complex formed obtained in

step b) with a reagent selected from another metal source, reducing reactants and/or nitriding reactants and/or oxidizing reactants.

8. Method of manufacturing a semiconductor structure, comprising the steps of the method of one of claims 6 to 7, wherein the substrate is a semiconductor substrate. 5
9. Method of manufacturing a photovoltaic structure, comprising the steps of the method of one of claims 6 to 7, wherein the substrate is a photovoltaic substrate. 10
10. Use of at least one compound as defined in one of claims 1 to 5 for the manufacturing of phase change materials (PCM). 15

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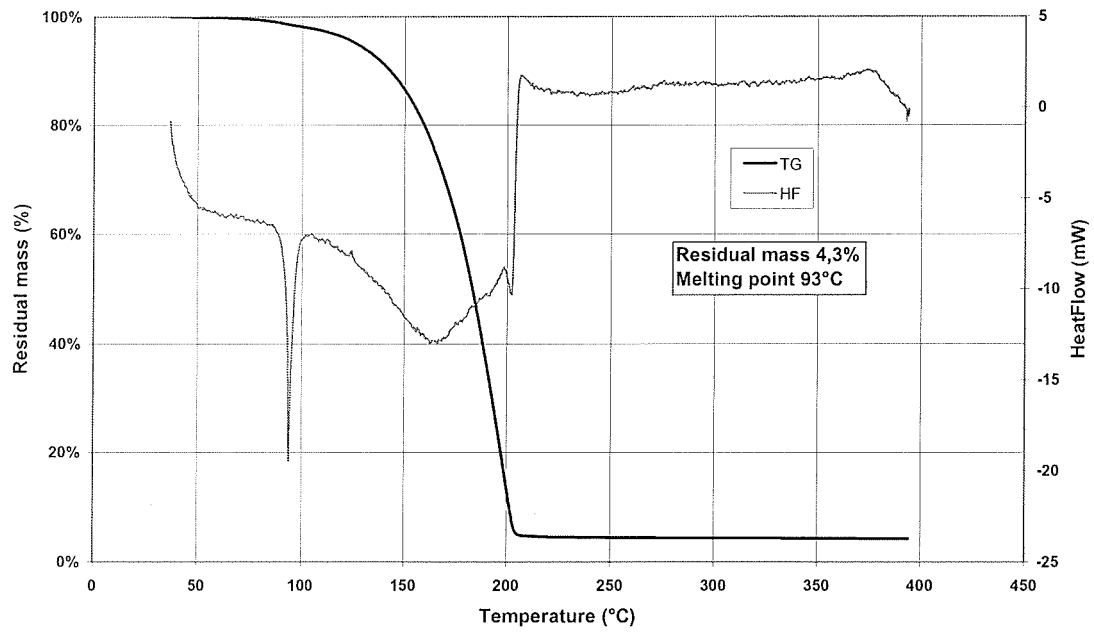


Figure 1

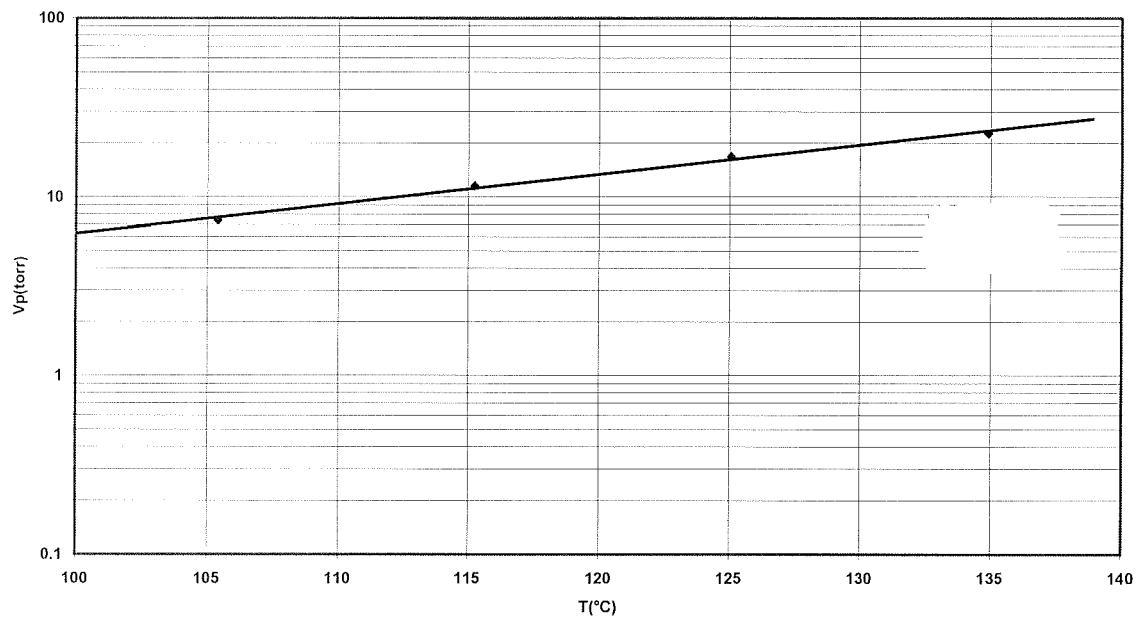


Figure 2



EUROPEAN SEARCH REPORT

Application Number
EP 11 30 5844

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (IPC)
X	WO 2010/126274 A2 (MECHARONICS CO LTD [KR]; JANG HYUK KYOO [KR]) 4 November 2010 (2010-11-04) * the whole document *	1,10	INV. C07F5/00 C23C16/00
E	WO 2011/111889 A1 (MECHARONICS CO LTD [KR]; JANG HYUK KYOO [KR]; KIM HYUN CHANG [KR]; LEE) 15 September 2011 (2011-09-15) * the whole document *	1,10	
X	EP 0 897 925 A2 (KOREA RES INST CHEM TECH [KR]) 24 February 1999 (1999-02-24) * example 1 *	1	
X	DATABASE CA [Online] CHEMICAL ABSTRACTS SERVICE, COLUMBUS, OHIO, US; 2009, lee, h. et al.: "Dimethylgallium isopropoxide as a new volatile source for ALD and MOCVD of Ga2O3", XP002664081, retrieved from STN Database accession no. 151:476186 * abstract *	1,10	
	& ECS TRANSACTIONS, vol. 25, no. 8, 2009, pages 587-592,		TECHNICAL FIELDS SEARCHED (IPC) C07F C23C
X	DATABASE CA [Online] CHEMICAL ABSTRACTS SERVICE, COLUMBUS, OHIO, US; 1989, Sato, K. et al.: "Manufacture of compound semiconductor films", XP002664082, retrieved from stn Database accession no. 113:8373 * abstract *	1,10	
	-/--		
The present search report has been drawn up for all claims			
Place of search The Hague		Date of completion of the search 26 April 2012	Examiner Rinkel, Bert
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			

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EPO FORM 1503 03.82 (P04C01)



EUROPEAN SEARCH REPORT

Application Number
EP 11 30 5844

DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (IPC)
X	& JP 1 319927 A (NIPPON TELEGRAPH & TELEPHONE) 26 December 1989 (1989-12-26) ----- DATABASE CA [Online] CHEMICAL ABSTRACTS SERVICE, COLUMBUS, OHIO, US; 1989, chikinova, n.v. et al.: "Reaction of organogallium peroxides with alcohols", XP002664083, retrieved from stn Database accession no. 112:158306 * abstract * & ZHURNAL OBSHCHEIKHIMII, vol. 59, no. 8, 1989, pages 1795-1798, -----	1,10	
A	DATABASE CA [Online] CHEMICAL ABSTRACTS SERVICE, COLUMBUS, OHIO, US; 1979, skachkov, b.k. et al.: "Phase diagram for the trimethylgallium-diethyl ether system", XP002674810, retrieved from STN Database accession no. 91:217612 * abstract * & Tulupov, V.A.: "Khim. Thermodin. Thermokin.", 1979, Moscow, USSR pages 98-100, -----	1	TECHNICAL FIELDS SEARCHED (IPC)
The present search report has been drawn up for all claims			
Place of search The Hague		Date of completion of the search 26 April 2012	Examiner Rinkel, Bert
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			

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EPO FORM 1503 03.82 (P04C01)



Application Number

EP 11 30 5844

CLAIMS INCURRING FEES

The present European patent application comprised at the time of filing claims for which payment was due.

☐ Only part of the claims have been paid within the prescribed time limit. The present European search report has been drawn up for those claims for which no payment was due and for those claims for which claims fees have been paid, namely claim(s):

☐ No claims fees have been paid within the prescribed time limit. The present European search report has been drawn up for those claims for which no payment was due.

LACK OF UNITY OF INVENTION

The Search Division considers that the present European patent application does not comply with the requirements of unity of invention and relates to several inventions or groups of inventions, namely:

see sheet B

☒ All further search fees have been paid within the fixed time limit. The present European search report has been drawn up for all claims.

☐ As all searchable claims could be searched without effort justifying an additional fee, the Search Division did not invite payment of any additional fee.

☐ Only part of the further search fees have been paid within the fixed time limit. The present European search report has been drawn up for those parts of the European patent application which relate to the inventions in respect of which search fees have been paid, namely claims:

☐ None of the further search fees have been paid within the fixed time limit. The present European search report has been drawn up for those parts of the European patent application which relate to the invention first mentioned in the claims, namely claims:

☐ The present supplementary European search report has been drawn up for those parts of the European patent application which relate to the invention first mentioned in the claims (Rule 164 (1) EPC).



**LACK OF UNITY OF INVENTION
SHEET B**

Application Number

EP 11 30 5844

The Search Division considers that the present European patent application does not comply with the requirements of unity of invention and relates to several inventions or groups of inventions, namely:

1. claims: 1, 10(all partially)

Compounds according to claim 1 wherein x equals 1 and their use

2. claims: 2-9(completely); 1, 10(partially)

Compounds according to claim 1 wherein x equals 2 and their use

**ANNEX TO THE EUROPEAN SEARCH REPORT
ON EUROPEAN PATENT APPLICATION NO.**

EP 11 30 5844

This annex lists the patent family members relating to the patent documents cited in the above-mentioned European search report.
The members are as contained in the European Patent Office EDP file on
The European Patent Office is in no way liable for these particulars which are merely given for the purpose of information.

26-04-2012

Patent document cited in search report	Publication date	Patent family member(s)	Publication date
WO 2010126274 A2	04-11-2010	NONE	
WO 2011111889 A1	15-09-2011	NONE	
EP 0897925 A2	24-02-1999	AT 234312 T	15-03-2003
		DE 69812012 D1	17-04-2003
		DE 69812012 T2	02-10-2003
		EP 0897925 A2	24-02-1999
		JP 3190893 B2	23-07-2001
		JP 11147888 A	02-06-1999
		US 5998644 A	07-12-1999